

Features

September 2011

- Internal control latches and address decoder
- Short set-up and hold times
- Wide operating voltage: 4.5V to 13.2V
- 12Vpp analog signal capability
- R_{ON} 65 Ω max. @ $V_{DD}=12V$, 25 $^{\circ}C$
- $\Delta R_{ON} \leq 10\Omega$ @ $V_{DD}=12V$, 25 $^{\circ}C$
- Full CMOS switch for low distortion
- Minimum feedthrough and crosstalk
- Separate analog and digital reference supplies
- Low power consumption ISO-CMOS technology

Applications

- Key systems
- PBX systems
- Mobile radio
- Test equipment /instrumentation
- Analog/digital multiplexers
- Audio/Video switching

Ordering Information

MT8815AP1	44 Pin PLCC*	Tubes
MT8815APR1	44 Pin PLCC*	Tape & Reel
MT8815AE1	40 Pin PDIP*	Tubes

*Pb Free Matte Tin

-40 $^{\circ}C$ to +85 $^{\circ}C$

Description

The Zarlink MT8815 is fabricated in Zarlink's ISO-CMOS technology providing low power dissipation and high reliability. The device contains a 8 x 12 array of crosspoint switches along with a 7 to 96 line decoder and latch circuits. Any one of the 96 switches can be addressed by selecting the appropriate seven address bits. The selected switch can be turned on or off by applying a logical one or zero to the DATA input. V_{SS} is the ground reference of the digital inputs. The range of the analog signal is from V_{DD} to V_{EE} .

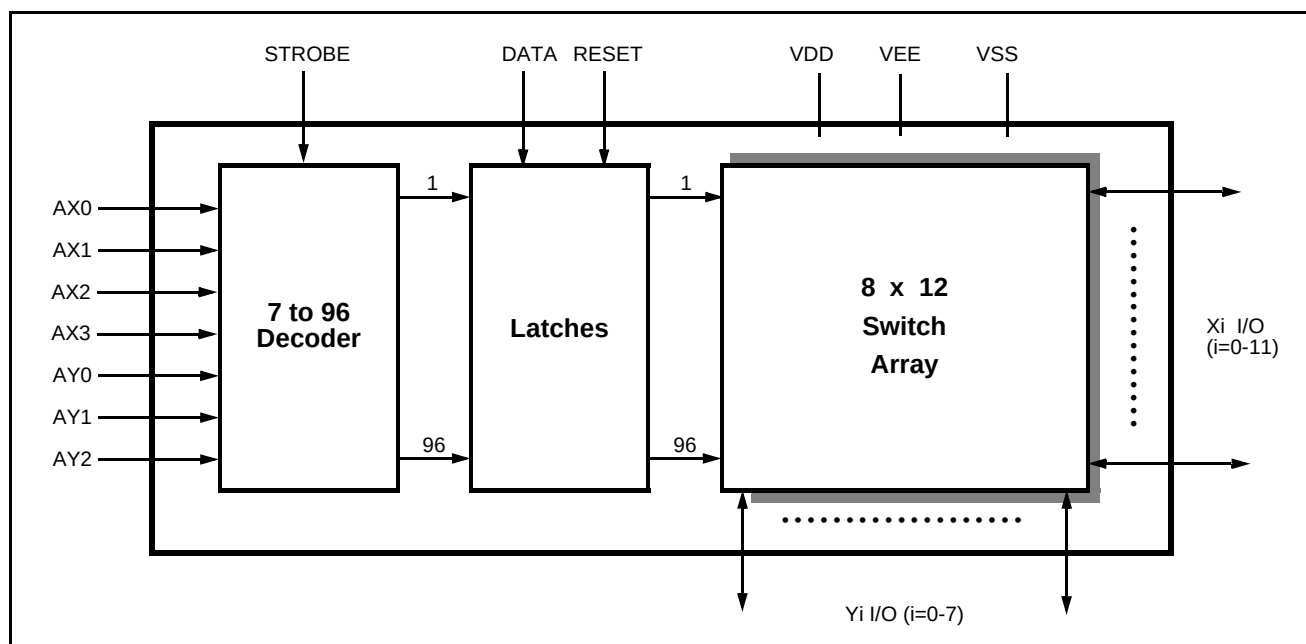


Figure 1 - Functional Block Diagram

Changes from the December 2008 issue to the September 2011 issue.

Changes from August 2005 to December 2008 issue.

40 PIN PLASTIC DIP

Pin	Label	Pin	Label
1	Y3	21	Y4
2	AY2	22	AX1
3	RESET	23	AX2
4	AX3	24	AY0
5	AX0	25	AY1
6	NC	26	NC
7	NC	27	NC
8	X6	28	X5
9	X7	29	X4
10	X8	30	X3
11	X9	31	X2
12	X10	32	X1
13	X11	33	X0
14	NC	34	NC
15	Y7	35	Y0
16	VSS	36	VDD
17	Y6	37	Y1
18	STROBE	38	DATA
19	Y5	39	Y2
20	VEE	40	NC

44 PIN PLCC

Pin	Label	Pin	Label
1	Y3	21	Y4
2	AY2	22	AX1
3	RESET	23	AX2
4	AX3	24	AY0
5	AX0	25	AY1
6	NC	26	NC
7	NC	27	NC
8	X6	28	X5
9	X7	29	X4
10	X8	30	X3
11	X9	31	X2
12	X10	32	X1
13	X11	33	X0
14	NC	34	NC
15	Y7	35	Y0
16	NC	36	Y1
17	Y6	37	Y2
18	VSS	38	DATA
19	STROBE	39	VDD
20	VEE	40	NC
21	Y5	41	NC
22	Y4	42	NC
23	Y3	43	NC
24	Y2	44	NC
25	Y1		
26	Y0		
27	NC		
28	NC		

Pin Description

Pin #		Name	Description
PDIP	PLCC		
1	1	Y3	Y3 Analog (Input/Output): this is connected to the Y3 column of the switch array.
2	2	AY2	Y2 Address Line (Input).
3	3	RESET	Master RESET (Input): this is used to turn off all switches. Active High.
4,5	4,5	AX3,AX0	X3 and X0 Address Lines (Inputs): these are used to select X3 and X0 rows of switches.
6,7	6-8	NC	No Connection.
8-13	9-14	X6-X11	X6-X11 Analog (Inputs/Outputs): these are connected to the X6-X11 rows of the switch array.

Pin Description

Pin #		Name	Description
PDIP	PLCC		
14	15,16	NC	No Connection
15	17	Y7	Y7 Analog (Input/Output): this is connected to the Y7 column of the switch array.
16	18	V _{SS}	Digital Ground Reference (Input).
17	19	Y6	Y6 Analog (Input/Output): this is connected to the Y6 column of the switch array.
18	20	STROBE	STROBE (Input): enables function selected by address and data. Address must be stable before STROBE goes high and DATA must be stable on the falling edge of the STROBE. Active High.
19	21	Y5	Y5 Analog (Input/Output): this is connected to the Y5 column of the switch array.
20	22	V _{EE}	Negative Power Supply.
21	23	Y4	Y4 Analog (Input/Output): this is connected to the Y4 column of the switch array.
22, 23	24,25	AX1,AX2	X1 and X2 Address Lines (Inputs).
24, 25	26,27	AY0,AY1	Y0 and Y1 Address Lines (Inputs).
26, 27	28-31	NC	No Connection.
28 - 33	32-37	X5-X0	X5-X0 Analog (Inputs/Outputs): these are connected to the X5-X0 rows of the switch array.
34	38	NC	No Connection.
35	39	Y0	Y0 Analog (Input/Output): this is connected to the Y0 column of the switch array.
36	40	V _{DD}	Positive Power Supply.
37	41	Y1	Y1 Analog (Input/Output): this is connected to the Y1 column of the switch array.
38	42	DATA	DATA (Input): a logic high input will turn on the selected switch and a logic low will turn off the selected switch. Active High.
39	43	Y2	Y2 Analog (Input/Output): this is connected to the Y2 column of the switch array.
40	44	NC	No Connection.

Functional Description

The MT8815 is an analog switch matrix with an array size of 8×12. The switch array is arranged such that there are 8 columns by 12 rows. The columns are referred to as the Y inputs/outputs and the rows are the X inputs/outputs. The crosspoint analog switch array will interconnect any X I/O with any Y I/O when turned on and provide a high degree of isolation when turned off. The control memory consists of a 96 bit write only RAM in which the bits are selected by the address inputs (AY0-AY2, AX0-AX3). Data is presented to the memory on the DATA input. Data is asynchronously written into memory whenever the STROBE input is high and is latched on the falling edge of STROBE. A logical “1” written into a memory cell turns the corresponding crosspoint switch on and a logical “0” turns the crosspoint off. Only the crosspoint switches corresponding to the addressed memory location are altered when data is written into memory. The remaining switches retain their previous states. Any combination of X and Y inputs/outputs can be interconnected by establishing appropriate patterns in the control memory. A logical “1” on the RESET input will asynchronously return all memory locations to logical “0” turning off all crosspoint switches. Two voltage reference pins (V_{SS} and V_{EE}) are provided for the MT8815 to enable switching of negative analog signals. The range for digital signals is from V_{DD} to V_{SS} while the range for analog signals is from V_{DD} to V_{EE} . V_{SS} and V_{EE} pins can be tied together if a single voltage reference is needed.

Address Decode

The seven address inputs along with the STROBE are logically ANDed to form an enable signal for the resettable transparent latches. The DATA input is buffered and is used as the input to all latches. To write to a location, RESET must be low while the address and data are set up. Then the STROBE input is set high and then low causing the data to be latched. The data can be changed while STROBE is high, however, the corresponding switch will turn on and off in accordance with the DATA input. DATA must be stable on the falling edge of STROBE in order for correct data to be written to the latch.

Absolute Maximum Ratings* - Voltages are with respect to V_{EE} unless otherwise stated.

	Parameter	Symbol	Min.	Max.	Units
1	Supply Voltage	V_{DD} V_{SS}	-0.3 -0.3	15.0 $V_{DD}+0.3$	V V
2	Analog Input Voltage	V_{INA}	-0.3	$V_{DD}+0.3$	V
3	Digital Input Voltage	V_{IN}	$V_{SS}-0.3$	$V_{DD}+0.3$	V
4	Current on any I/O Pin	I		± 15	mA
5	Storage Temperature	T_S	-65	+150	°C
6	Package Power Dissipation PLASTIC DIP	P_D		0.6	W

* Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

Recommended Operating Conditions - Voltages are with respect to V_{EE} unless otherwise stated.

	Characteristics	Sym.	Min.	Typ.	Max.	Units	Test Conditions
1	Operating Temperature	T_O	-40	25	85	°C	
2	Supply Voltage	V_{DD} V_{SS}	4.5 V_{EE}		13.2 $V_{DD}-4.5$	V V	
3	Analog Input Voltage	V_{INA}	V_{EE}		V_{DD}	V	
4	Digital Input Voltage	V_{IN}	V_{SS}		V_{DD}	V	

DC Electrical Characteristics[†] - Voltages are with respect to $V_{EE}=V_{SS}=0V$, $V_{DD}=12V$ unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Quiescent Supply Current	I_{DD}		1	100	μA	All digital inputs at $V_{IN}=V_{SS}$ or V_{DD}
				0.4	1.5	mA	All digital inputs at $V_{IN}=2.4V + V_{SS}$; $V_{SS}=7.0V$
				5	15	mA	All digital inputs at $V_{IN}=3.4V$
2	Off-state Leakage Current (See G.9 in Appendix)	I_{OFF}		± 1	± 500	nA	$ V_{Xi} - V_{Yj} = V_{DD} - V_{EE}$ See Appendix, Fig. A.1
3	Input Logic "0" level	V_{IL}			$0.8+V_{SS}$	V	$V_{SS}=7.5V$; $V_{EE}=0V$
4	Input Logic "1" level	V_{IH}	$2.0+V_{SS}$			V	$V_{SS}=6.5V$; $V_{EE}=0V$
5	Input Logic "1" level	V_{IH}	3.3			V	
6	Input Leakage (digital pins)	I_{LEAK}		0.1	10	μA	All digital inputs at $V_{IN} = V_{SS}$ or V_{DD}

[†] DC Electrical Characteristics are over recommended temperature range.

[‡] Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

DC Electrical Characteristics- Switch Resistance - V_{DC} is the external DC offset applied at the analog I/O pins.

	Characteristics	Sym	25°C		70°C		85°C		Units	Test Conditions
			Typ.	Max.	Typ.	Max.	Typ.	Max.		
1	On-state Resistance $V_{DD}=12V$ $V_{DD}=10V$ $V_{DD}=5V$ (See G.1, G.2, G.3 in Appendix)	R_{ON}	45 55 120	65 75 185		75 85 215		80 90 225	Ω Ω Ω	$V_{SS}=V_{EE}=0V, V_{DC}=V_{DD}/2$, $ V_{Xi}-V_{Yj} = 0.4V$ See Appendix, Fig. A.2
2	Difference in on-state resistance between two switches (See G.4 in Appendix)	ΔR_{ON}	5	10		10		10	Ω	$V_{DD}=12V, V_{SS}=V_{EE}=0$, $V_{DC}=V_{DD}/2$, $ V_{Xi}-V_{Yj} = 0.4V$ See Appendix, Fig. A.2

AC Electrical Characteristics[†] - Crosspoint Performance- Voltages are with respect to $V_{DD}=5V, V_{SS}=0V, V_{EE}=-7V$, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Switch I/O Capacitance	C_S		20		pF	f=1 MHz
2	Feedthrough Capacitance	C_F		0.2		pF	f=1 MHz
3	Frequency Response Channel "ON" $20\text{LOG}(V_{OUT}/V_{Xi})=-3\text{dB}$	$F_{3\text{dB}}$		45		MHz	Switch is "ON"; $V_{INA} = 2V_{pp}$ sinewave; $R_L = 1k\Omega$ See Appendix, Fig. A.3
4	Total Harmonic Distortion (See G.5, G.6 in Appendix)	THD		0.01		%	Switch is "ON"; $V_{INA} = 2V_{pp}$ sinewave f= 1kHz; $R_L=1k\Omega$
5	Feedthrough Channel "OFF" Feed.= $20\text{LOG}(V_{OUT}/V_{Xi})$ (See G.8 in Appendix)	FDT		-95		dB	All Switches "OFF"; $V_{INA}=2V_{pp}$ sinewave f= 1kHz; $R_L = 1k\Omega$. See Appendix, Fig. A.4
6	Crosstalk between any two channels for switches Xi-Yi and Xj-Yj. $X_{\text{talk}}=20\text{LOG}(V_{Yj}/V_{Xi})$. (See G.7 in Appendix).	X_{talk}		-45		dB	$V_{INA}=2V_{pp}$ sinewave f= 10MHz; $R_L = 75\Omega$.
				-90		dB	$V_{INA}=2V_{pp}$ sinewave f= 10kHz; $R_L = 600\Omega$.
				-85		dB	$V_{INA}=2V_{pp}$ sinewave f= 10kHz; $R_L = 1k\Omega$.
				-80		dB	$V_{INA}=2V_{pp}$ sinewave f= 1kHz; $R_L = 10k\Omega$. Refer to Appendix, Fig. A.5 for test circuit.
7	Propagation delay through switch	t_{PS}			30	ns	$R_L=1k\Omega; C_L=50pF$

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.

[‡] Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

Crosstalk measurements are for Plastic DIPS only, crosstalk values for PLCC packages are approximately 5 dB better.

AC Electrical Characteristics[†] - Control and I/O Timings- Voltages are with respect to $V_{DD}=5V$, $V_{SS}=0V$,
 $V_{EE}=-7V$, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Control Input crosstalk to switch (for DATA, STROBE, Address)	CX_{talk}		30		mVpp	$V_{IN}=3V$ squarewave; $R_{IN}=1k\Omega$, $R_L=10k\Omega$. See Appendix, Fig. A.6
2	Digital Input Capacitance	C_{DI}		10		pF	$f=1MHz$
3	Switching Frequency	F_O			20	MHz	
4	Setup Time DATA to STROBE	t_{DS}	10			ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
5	Hold Time DATA to STROBE	t_{DH}	10			ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
6	Setup Time Address to STROBE	t_{AS}	10			ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
7	Hold Time Address to STROBE	t_{AH}	10			ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
8	STROBE Pulse Width	t_{SPW}	20			ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
9	RESET Pulse Width	t_{RPW}	40			ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
10	STROBE to Switch Status Delay	t_S		40	100	ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
11	DATA to Switch Status Delay	t_D		50	100	ns	$R_L=1k\Omega$, $C_L=50pF$ ¹
12	RESET to Switch Status Delay	t_R		35	100	ns	$R_L=1k\Omega$, $C_L=50pF$ ¹

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.

Digital Input rise time (t_r) and fall time (t_f) = 5ns.

[‡] Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

¹ Refer to Appendix, Fig. A.7 for test circuit.

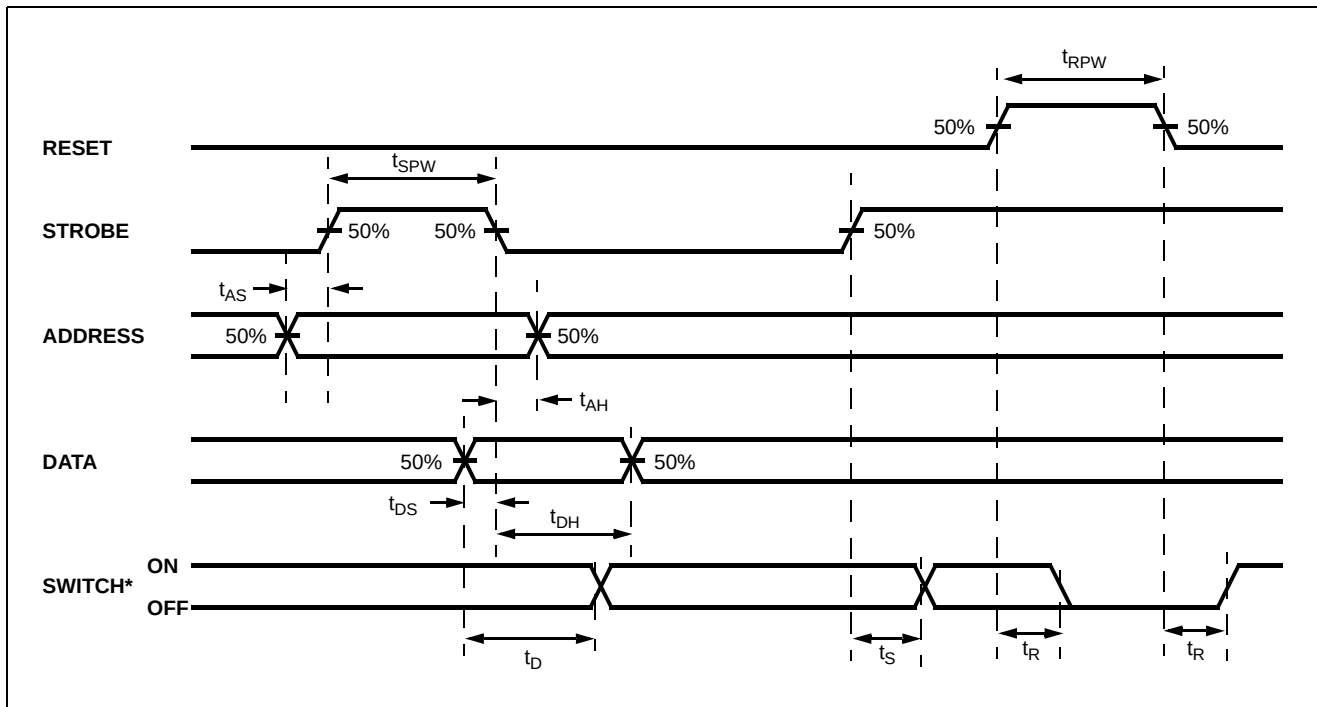


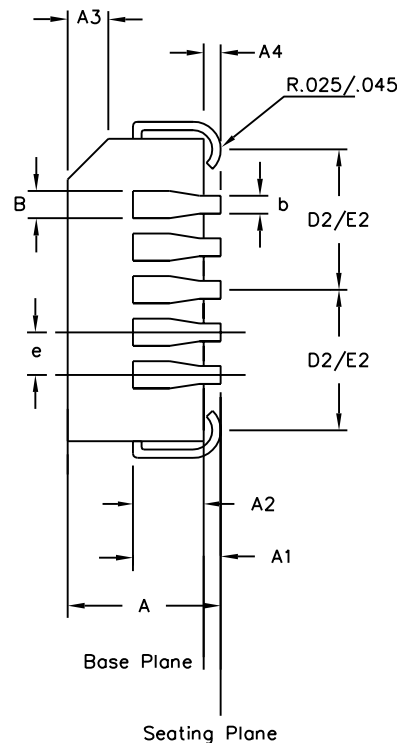
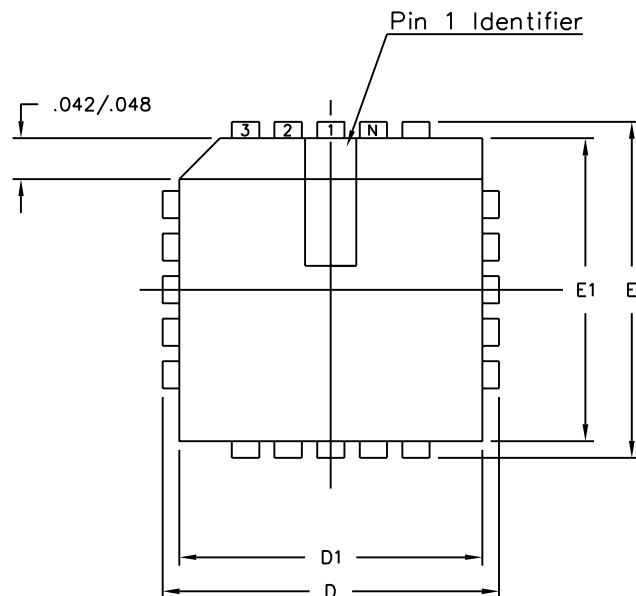
Figure 3 - Control Memory Timing Diagram

* See Appendix, Fig. A.7 for switching waveform

AX0	AX1	AX2	AX3	AY0	AY1	AY2	Connection
0	0	0	0	0	0	0	X0-Y0
1	0	0	0	0	0	0	X1-Y0
0	1	0	0	0	0	0	X2-Y0
1	1	0	0	0	0	0	X3-Y0
0	0	1	0	0	0	0	X4-Y0
1	0	1	0	0	0	0	X5-Y0
0	1	1	0	0	0	0	No Connection
1	1	1	0	0	0	0	No Connection
0	0	0	1	0	0	0	X6-Y0
1	0	0	1	0	0	0	X7-Y0
0	1	0	1	0	0	0	X8-Y0
1	1	0	1	0	0	0	X9-Y0
0	0	1	1	0	0	0	X10-Y0
1	0	1	1	0	0	0	X11-Y0
0	1	1	1	0	0	0	No Connection
1	1	1	1	0	0	0	No Connection
0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	0 ↓	0 ↓	X0-Y1 ↓
1	0	1	1	1	0	0	X11-Y1
0 ↓	0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	0 ↓	X0-Y2 ↓
1	0	1	1	0	1	0	X11-Y2
0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	1 ↓	0 ↓	X0-Y3 ↓
1	0	1	1	1	1	0	X11-Y3
0 ↓	0 ↓	0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	X0-Y4 ↓
1	0	1	1	0	0	1	X11-Y4
0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	0 ↓	1 ↓	X0-Y5 ↓
1	0	1	1	1	0	1	X11-Y5
0 ↓	0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	1 ↓	X0-Y6 ↓
1	0	1	1	0	1	1	X11-Y6
0 ↓	0 ↓	0 ↓	0 ↓	1 ↓	1 ↓	1 ↓	X0-Y7 ↓
1	0	1	1	1	1	1	X11-Y7

Table 1 - Address Decode Truth Table

This address has no effect on device status.



Symbol	Control Dimensions in inches		Altern. Dimensions in millimetres	
	MIN	MAX	MIN	MAX
A	0.165	0.180	4.19	4.57
A1	0.090	0.120	2.29	3.05
A2	0.062	0.083	1.57	2.11
A3	0.042	0.056	1.07	1.42
A4	0.020	—	0.51	—
D	0.685	0.695	17.40	17.65
D1	0.650	0.656	16.51	16.66
D2	0.291	0.319	7.39	8.10
E	0.685	0.695	17.40	17.65
E1	0.650	0.656	16.51	16.66
E2	0.291	0.319	7.39	8.10
B	0.026	0.032	0.66	0.81
b	0.013	0.021	0.33	0.53
e	0.050	BSC	1.27	BSC
	Pin features			
ND	11			
NE	11			
N	44			
Note	Square			
Conforms to JEDEC MS-018AC Iss. A				

Notes:

1. All dimensions and tolerances conform to ANSI Y14.5M-1982
2. Dimensions D1 and E1 do not include mould protrusions. Allowable mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion mismatch and are determined at the parting line, that is D1 and E1 are measured at the extreme material condition at the upper or lower parting line.
3. Controlling dimensions in Inches.
4. "N" is the number of terminals.
5. Not To Scale
6. Dimension R required for 120° minimum bend.

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ISSUE	1	2	3	
ACN	5958	207470	213094	
DATE	15Aug94	10Sep99	15Jul02	
APPRD.				



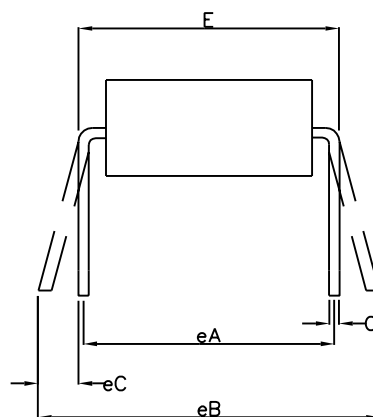
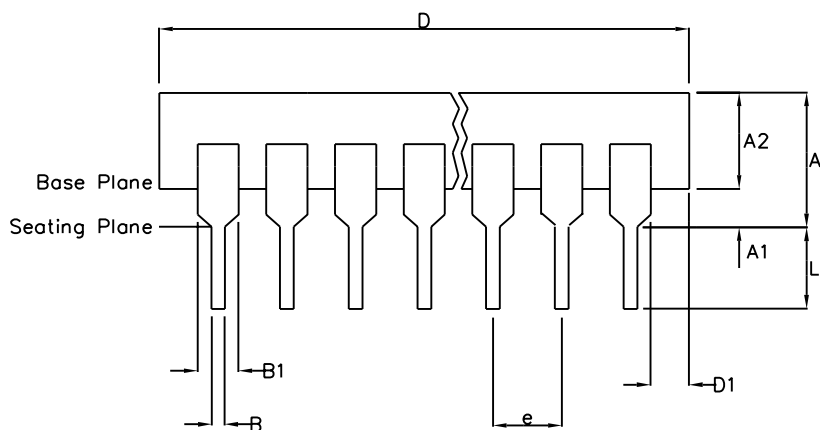
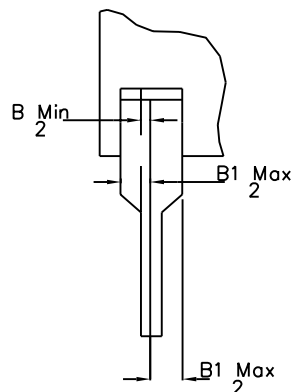
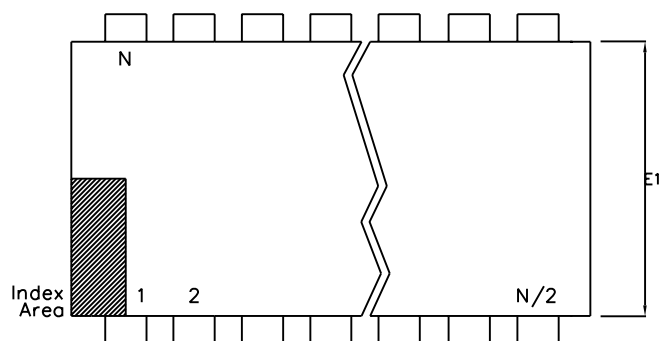
Previous package codes

HP / P

Package Code QA

Package Outline for
44 lead PLCC

GPD000003



	Min mm	Max mm	Min Inches	Max Inches
A		6.35		0.250
A1	0.38		0.015	
A2	3.18	4.95	0.125	0.195
B	0.36	0.56	0.014	0.022
B1	0.76	1.78	0.030	0.070
C	0.20	0.38	0.008	0.015
D	50.29	53.21	1.980	2.095
D1	0.13		0.005	
E	15.24	15.88	0.600	0.625
E1	12.32	14.73	0.485	0.580
e	2.54 BSC		0.100 BSC	
eA	15.24 BSC		0.600 BSC	
eB		17.78		0.700
L	2.92	5.08	0.115	0.200
N	40		40	
Conforms to Jedec MS-011AC ISS.B				

Notes:

1. Controlling Dimensions are in inches
2. Dimension A, A1 and L are measured with the package seated in the Seating Plane
3. Dimensions D & E1 do not include mould flash or protrusions. Mould flash or protrusion shall not exceed 0.010 inch.
4. Dimensions E & eA are measured with leads constrained to be perpendicular to plane T.
5. Dimensions eB & eC are measured at the lead tips with the leads unconstrained; eC must be zero or greater.

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ISSUE	1	2	3		Previous package codes	Package Outline for 40 lead PDIP
ACN	7010	203533	213103		DP / E	
DATE	20Apr95	25Nov97	15Jul02			GPD000073
APPRD.						



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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9